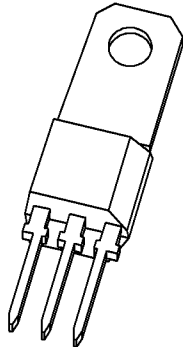


DATA SHEET



BF870; BF872 PNP high-voltage transistors

Product specification
Supersedes data of 1996 Dec 09

1998 Sep 21

Philips
Semiconductors



PHILIPS

PNP high-voltage transistors

BF870; BF872

FEATURES

- Low feedback capacitance.

APPLICATIONS

- For use in class-B video output stages of colour television receivers.

DESCRIPTION

PNP transistors in a TO-202 plastic package.
NPN complements: BF869 and BF871.

PINNING

PIN	DESCRIPTION
1	emitter
2	collector, connected to mounting base
3	base

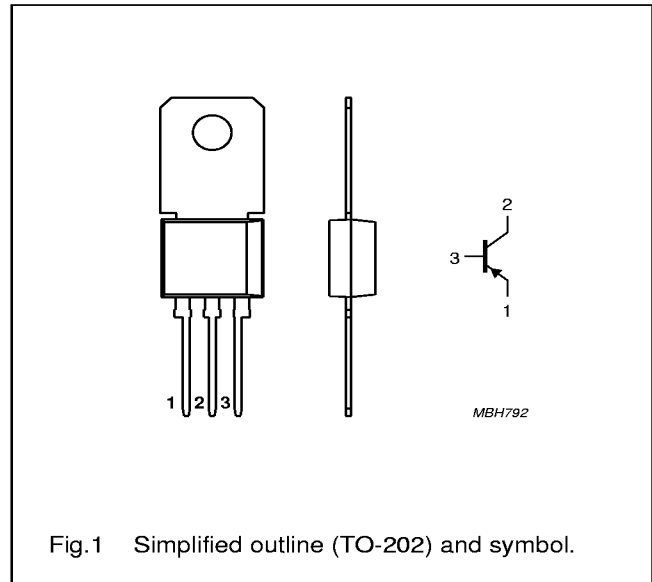


Fig. 1 Simplified outline (TO-202) and symbol.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter			
	BF870		–	–250	V
	BF872		–	–300	V
V_{CEO}	collector-emitter voltage	open base			
	BF870		–	–250	V
	BF872		–	–300	V
I_{CM}	peak collector current		–	–100	mA
P_{tot}	total power dissipation	$T_{mb} \leq 25\text{ °C}$	–	5	W
h_{FE}	DC current gain	$I_C = -25\text{ mA}; V_{CE} = -20\text{ V}; T_j = 25\text{ °C}$	50	–	
C_{re}	feedback capacitance	$I_C = I_C = 0; V_{CE} = -30\text{ V}; f = 1\text{ MHz}$	–	2.2	pF
f_T	transition frequency	$I_C = -10\text{ mA}; V_{CE} = -10\text{ V}; f = 100\text{ MHz}$	60	–	MHz

PNP high-voltage transistors

BF870; BF872

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage BF870 BF872	open emitter	–	–250	V
			–	–300	V
V _{CEO}	collector-emitter voltage BF870 BF872	open base	–	–250	V
			–	–300	V
V _{EBO}	emitter-base voltage	open collector	–	–5	V
I _C	collector current (DC)		–	–50	mA
I _{CM}	peak collector current		–	–100	mA
I _{BM}	peak base current		–	–50	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C	–	1.6	W
		T _{mb} ≤ 25 °C	–	5	W
T _{stg}	storage temperature		–65	+150	°C
T _j	junction temperature		–	150	°C
T _{amb}	operating ambient temperature		–65	+150	°C

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
R _{th j-a}	thermal resistance from junction to ambient	78	K/W
R _{th j-mb}	thermal resistance from junction to mounting base	25	K/W

CHARACTERISTICST_j = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I _{CBO}	collector cut-off current	I _E = 0; V _{CB} = –200 V	–	–10	nA
		I _E = 0; V _{CB} = –200 V; T _j = 150 °C	–	–10	μA
I _{EBO}	emitter cut-off current	I _C = 0; V _{EB} = –5 V	–	–50	nA
h _{FE}	DC current gain	I _C = –25 mA; V _{CE} = –20 V	50	–	
V _{CEsat}	collector-emitter saturation voltage	I _C = –30 mA; I _B = –5 mA	–	–600	mV
C _{re}	feedback capacitance	I _C = I _c = 0; V _{CE} = –30 V; f = 1MHz	–	2.2	pF
f _T	transition frequency	I _C = –10 mA; V _{CE} = –10 V; f = 100 MHz	60	–	MHz

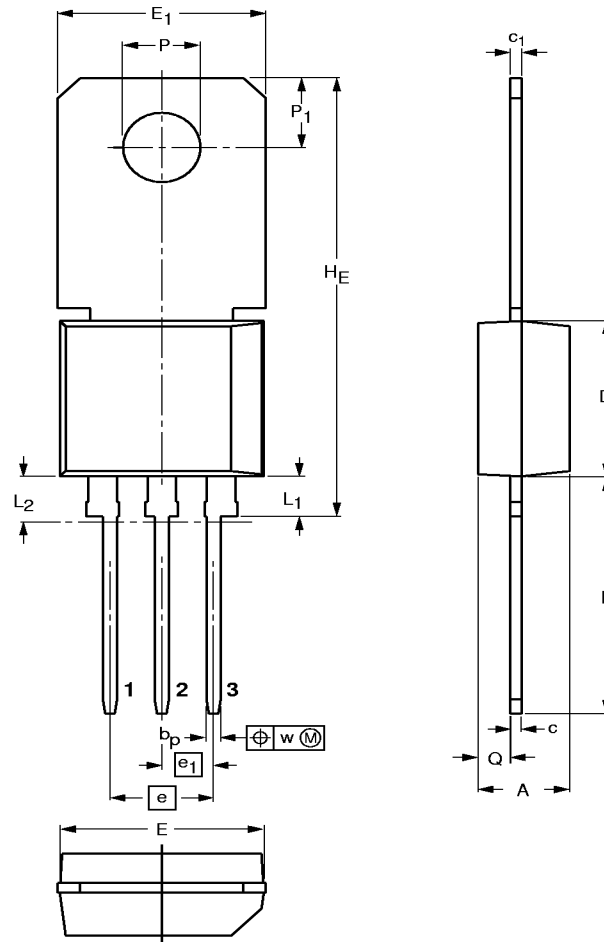
PNP high-voltage transistors

BF870; BF872

PACKAGE OUTLINE

Plastic single-ended leaded (through hole) package; with cooling fin, mountable to heatsink, 1 mounting hole; 3 leads (in-line)

SOT128B



DIMENSIONS (mm are the original dimensions)

UNIT	A	bp	c	c1	D	E	E1	e	e1	HE	L	L1	L2 ⁽¹⁾ max	P	P1	Q	w
mm	4.6 4.4	0.8 0.6	0.65 0.5	0.56 0.46	8.6 8.4	10.1 9.9	10.4 10.0	5.08	2.54	24.2 23.8	13.3 12.2	2.4 2.0	2.5	3.8 3.6	3.9 3.7	1.7 1.5	0.25

Note

1. Plastic flash allowed within this zone

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT128B		TO-202				97-02-28